TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (Ultra-High-Speed U-MOSIII)

TPC8021-H

High-Efficiency DC/DC Converter Applications Notebook PC Applications Portable-Equipment Applications

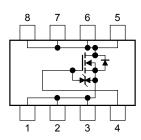
- Small footprint due to a small and thin package
- High-speed switching
- Small gate charge: QSW = 3.6 nC (typ.)
- Low drain-source ON-resistance: R_{DS} (ON) = 13.5 m Ω (typ.)
- High forward transfer admittance: $|Y_{fs}|$ =19 S (typ.)
- Low leakage current: $I_{DSS} = 10 \mu A (max) (V_{DS} = 30 V)$
- Enhancement mode: $V_{th} = 1.1 \text{ to } 2.3 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$

Absolute Maximum Ratings (Ta = 25°C)

Characte	eristic	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	30	٧	
Drain-gate voltage (R	$k_{GS} = 20 \text{ k}\Omega$)	V_{DGR}	30	V	
Gate-source voltage		V_{GSS}	±20	V	
Drain current	DC (Note 1)	I _D	11	Α	
Diain current	Pulsed (Note 1)	I_{DP}	44		
Drain power dissipation	on $(t = 10 s)$ (Note 2a)	P_{D}	1.9	W	
Drain power dissipation	on (t = 10 s) (Note 2b)	P _D	1.0	W	
Single-pulse avalance	he energy (Note 3)	E _{AS}	79	mJ	
Avalanche current		I _{AR}	11	Α	
Repetitive avalanche	energy Note 2a) (Note 4)	E _{AR}	0.14	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature	range	T _{stg}	-55 to 150	°C	

Weight: 0.085 g (typ.)

Circuit Configuration



Note: Note 1, Note 2, Note 3 and Note 4: See the next page.

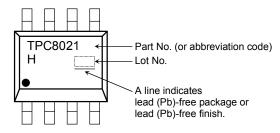
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

This transistor is an electrostatic-sensitive device. Handle with care.

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R _{th (ch-a)}	65.8	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R _{th (ch-a)}	125	°C/W

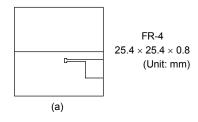
Marking (Note 5)

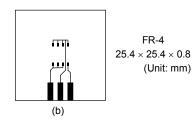


Note 1: The channel temperature should not exceed 150°C during use.

Note 2: (a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)



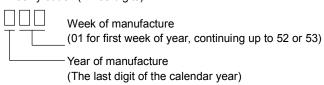


Note 3: $V_{DD} = 24~V$, $T_{ch} = 25^{\circ}C$ (initial), L = 0.5~mH, $R_G = 25~\Omega$, $I_{AR} = 11~A$

Note 4: Repetitive rating: pulse width limited by max channel temperature

Note 5: • on the lower left of the marking indicates Pin 1.

* Weekly code: (Three digits)

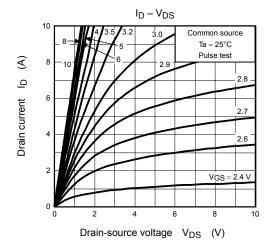


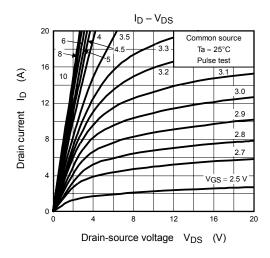
Electrical Characteristics (Ta = 25°C)

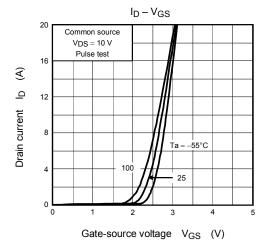
Ch	Characteristic		Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Drain cutoff curre	ent	I _{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$		_	10	μА
Drain-source breakdown voltage		V (BR) DSS	$I_D = 10$ mA, $V_{GS} = 0$ V	30	_	_	V
Diain-source bre	akdowii vollage	V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	15 — —		V	
Gate threshold vo	oltage	V _{th}	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$	1.1	_	2.3	V
Drain source ON	rocietanos	Б	$V_{GS} = 4.5 \text{ V}, I_D = 5.5 \text{ A}$	_	18.5	25	mO
Drain-source ON-resistance		R _{DS} (ON)	$V_{GS} = 10 \text{ V}, I_D = 5.5 \text{ A}$	_	13.5	17	mΩ
Forward transfer	admittance	tance $ Y_{fs} $ $V_{DS} = 10 \text{ V}, I_D = 5.5 \text{ A}$		10	19	_	S
Input capacitance	Input capacitance C _{iss}			_	640	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		75	_	pF
Output capacitance		C _{oss}			300	_	
	Rise time	t _r	Acs 0 A D S S S S S S S S S S S S S S S S S S	_	4	_	ns
	Turn-on time	t _{on}		_	8	_	
Switching time	Fall time	t _f		_	4	_	
	Turn-off time	t _{off}	$V_{DD} \simeq 15 \text{ V}$ Duty \leq 1%, $t_W = 10 \mu\text{s}$	_	18	_	
Total gate charge		0	$V_{DD} \simeq 24 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 11 \text{ A}$		11	_	
(gate-source plus	e-source plus gate-drain)		$V_{DD} \simeq 24 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 11 \text{ A}$	_	6.3	_	
Gate-source charge 1		Q _{gs1}	$V_{DD} \simeq 24 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 11 \text{A}$		2.2	_	nC
Gate-drain ("Miller") charge		Q _{gd}			2.6	_	
Gate switch charge		Q_{SW}		_	3.6	_	

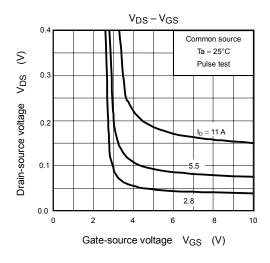
Source-Drain Ratings and Characteristics (Ta = 25°C)

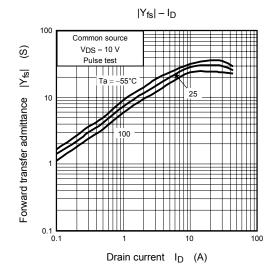
Character	istic		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse	(Note 1)	I _{DRP}	_	_	_	44	Α
Forward voltage (diode)			V_{DSF}	$I_{DR} = 15 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.2	V

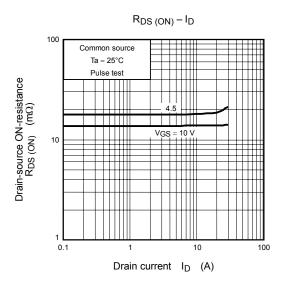


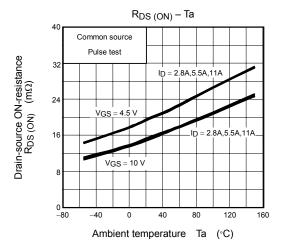


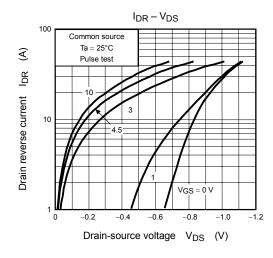


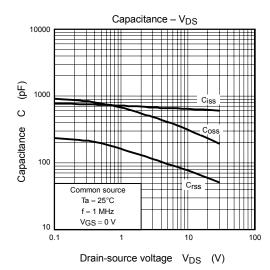


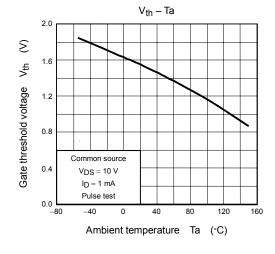


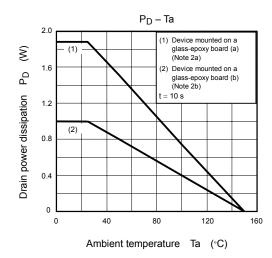


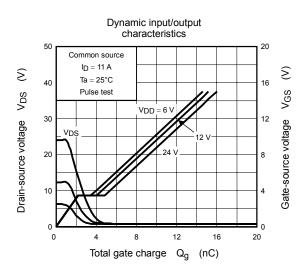


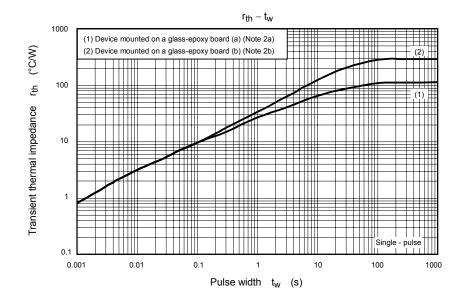


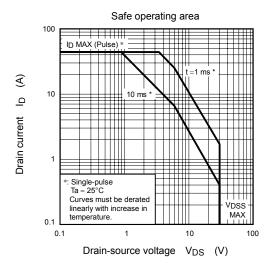












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